

## **Notification about the transfer of the semiconductor business**

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

※ Except below description page

"Request for your special attention and precautions in using the technical information and semiconductors described in this book"

**Nuvoton Technology Corporation Japan**



**MTM232230LBF**  
 Silicon N-channel MOS FET

For switching

■ Features

- Low drain-source On-state resistance : RDS(on) typ = 20 mΩ (VGS = 4.0 V)
- Low drive voltage: 2.5 V drive  
 Halogen-free / RoHS compliant  
 (EU RoHS / UL-94 V-0 / MSL : Level 1 compliant)

■ Marking Symbol : BK

■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

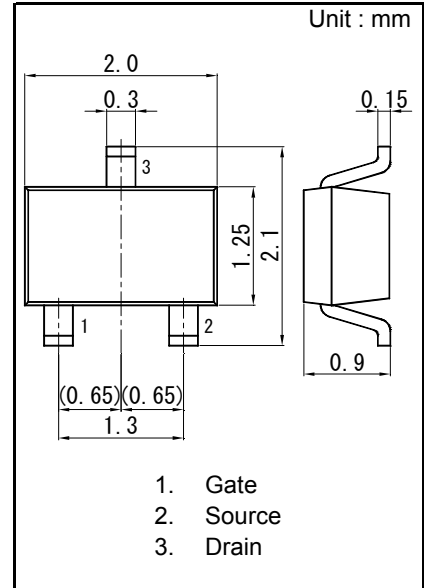
■ Absolute Maximum Ratings Ta = 25 °C

項目	記号	定格	単位
Drain-source Voltage	VDS	20	V
Gate-source Voltage	VGS	±10	
Drain current	ID	4.5	A
Peak drain current *1	IDp	18	A
Power dissipation *2	PD	500	mW
Channel temperature	Tch	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage Temperature Range	Tstg	-55 to +150	°C

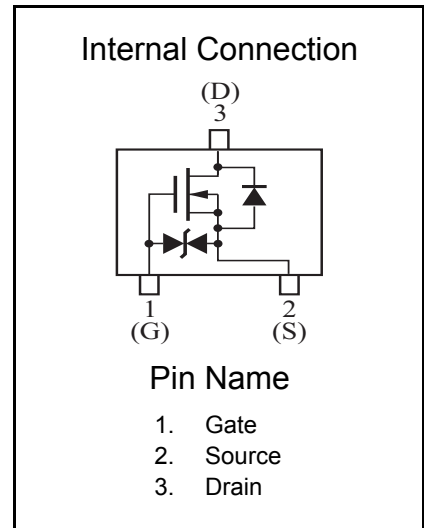
Note) \*1 Pulse width ≤ 10 μs, Duty cycle ≤ 1 %

\*2 Measuring on ceramic board at 40 × 38 × 0.1 mm

Absolute maximum rating PD without heat sink shall be made 150 mW.



Panasonic	SMini3-G1-B
JEITA	SC-70
Code	SOT-323



■ Electrical Characteristics Ta = 25 °C ± 3 °C

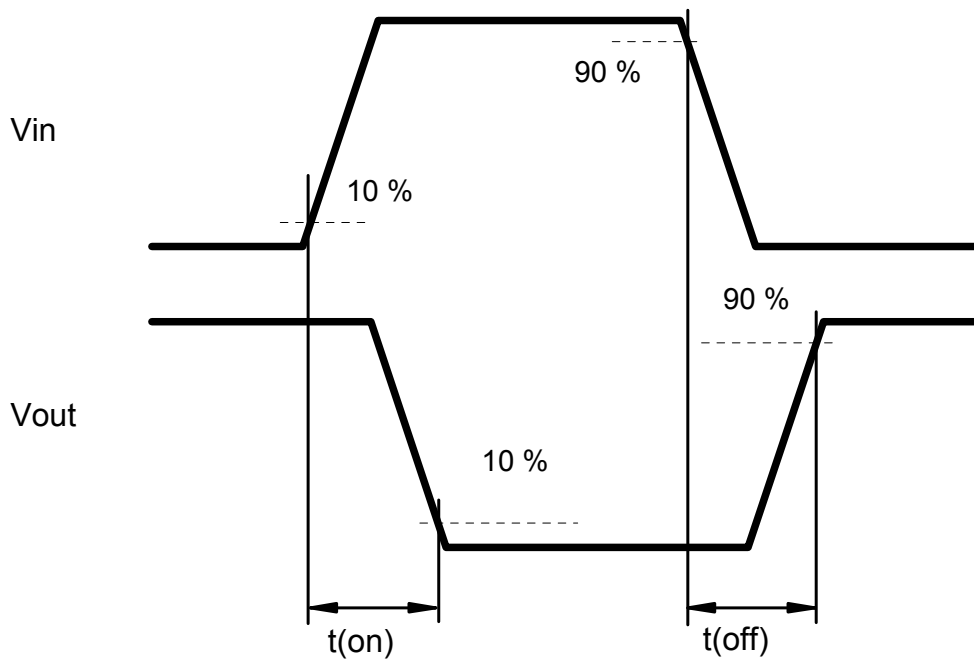
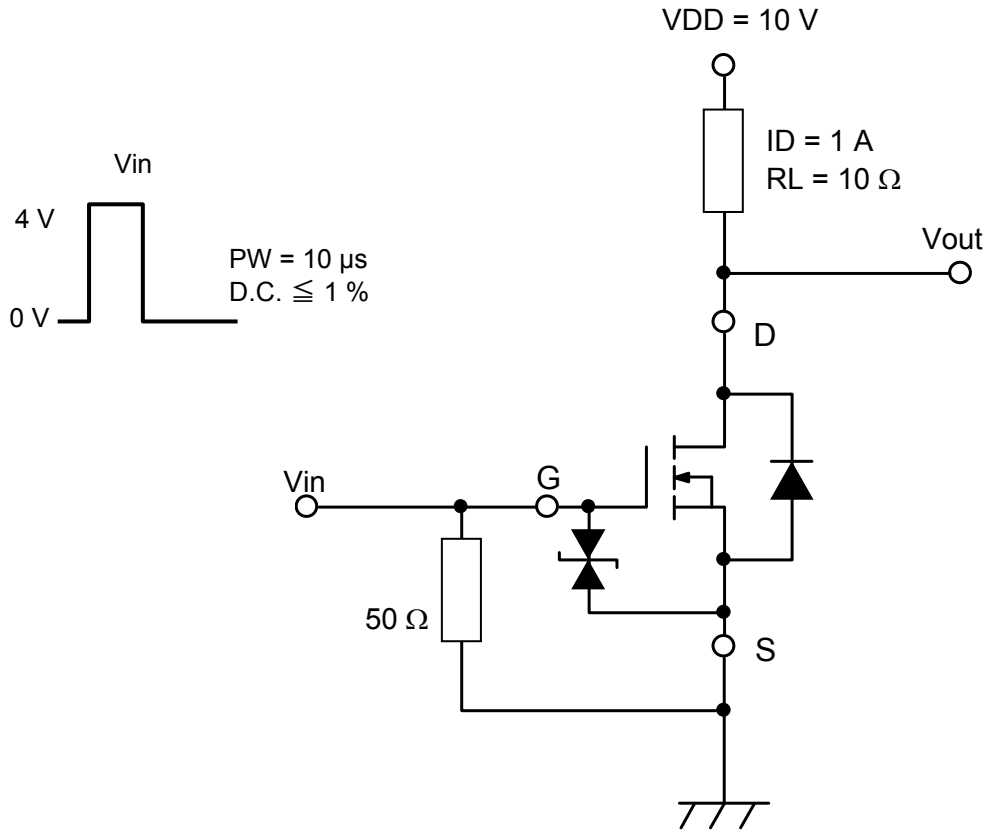
項目	記号	条件	最小	標準	最大	単位
Drain-source surrender voltage	VDSS	ID = 1 mA, VGS = 0 V	20			V
Drain-source cutoff current	IDSS	VDS = 20 V, VGS = 0 V			1.0	μA
Gate-source cutoff current	IGSS	VGS = ±8 V, VDS = 0 V			±10	μA
Gate threshold voltage	Vth	ID = 1.0 mA, VDS = 10.0 V	0.4	0.85	1.3	V
Drain-source ON resistance *1	RDS(ON)1	ID = 1 A, VGS = 4 V		20	28	mΩ
	RDS(ON)2	ID = 0.6 A, VGS = 2.5 V		26	40	
Forward transfer admittance *1	Yfs	ID = 1 A, VDS = 10 V, f = 1 kHz	3.5			S
Short-circuit input capacitance (Common source)	Ciss	VDS = 10 V, VGS = 0, f = 1 MHz		1 200		pF
Short-circuit output capacitance (Common source)	Coss			85		
Reverse transfer capacitance (Common source)	Crss			80		
Turn-on Time *2	ton	VDD = 10 V, VGS = 0 to 4 V ID = 1 A		16		ns
Turn-off Time *2	toff	VDD = 10 V, VGS = 4 to 0 V ID = 1 A		220		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

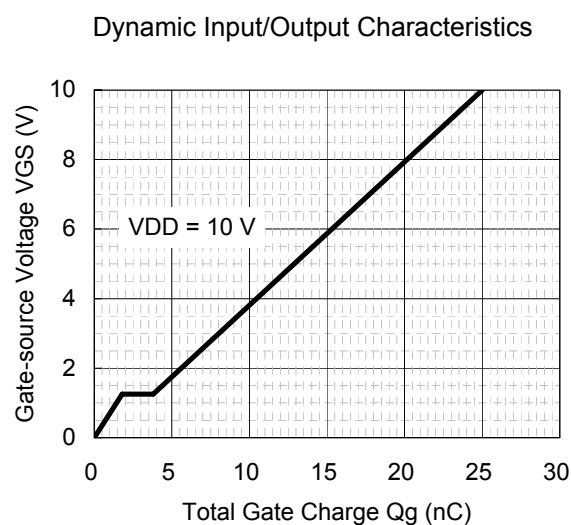
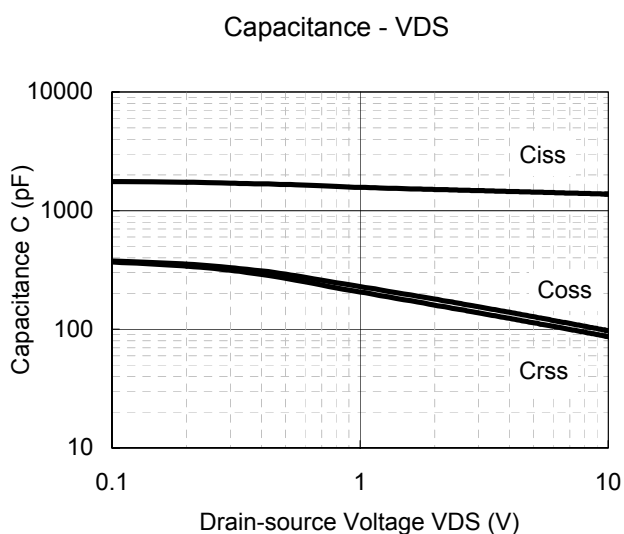
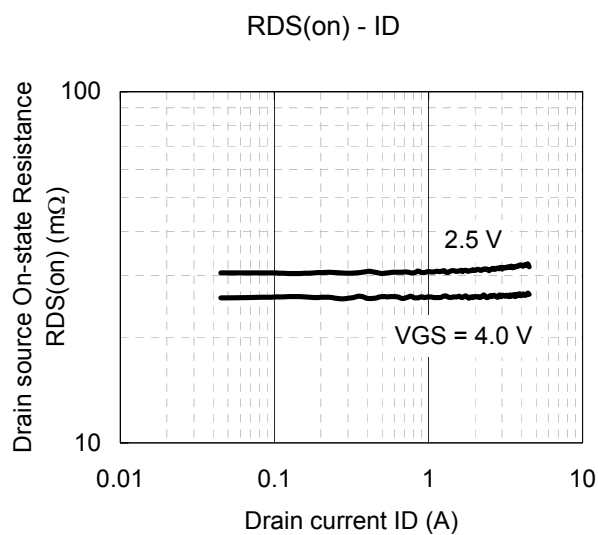
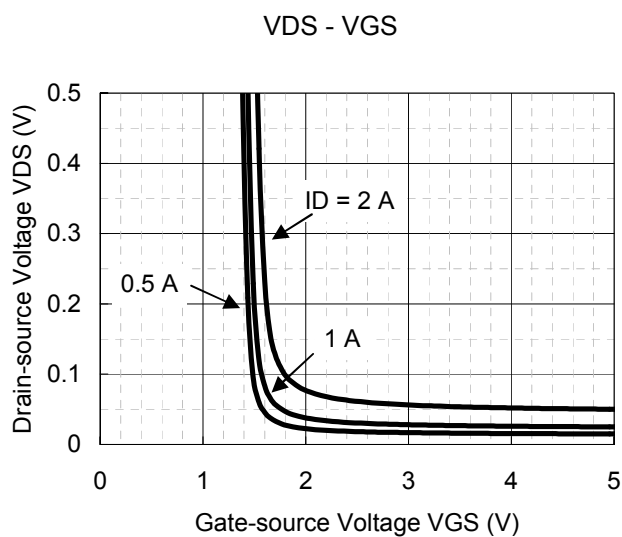
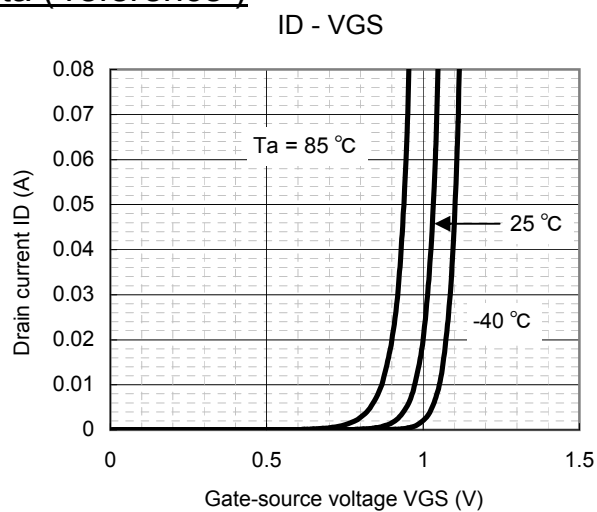
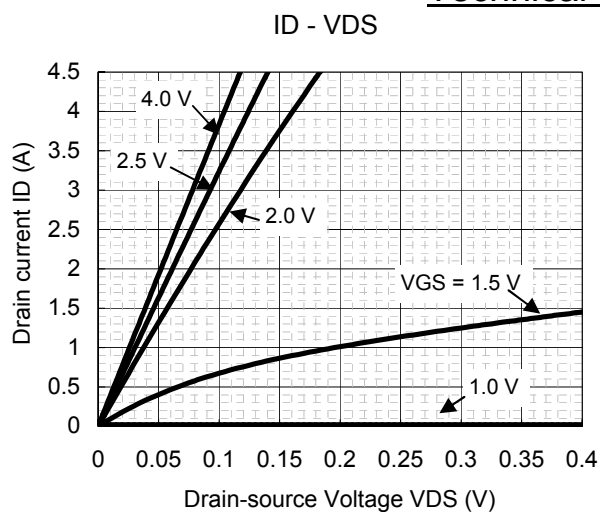
2. \*1 Pulse test : Pulse width < 300 μs, Duty cycle < 2 %

\*2 Turn-on and Turn-off test circuit

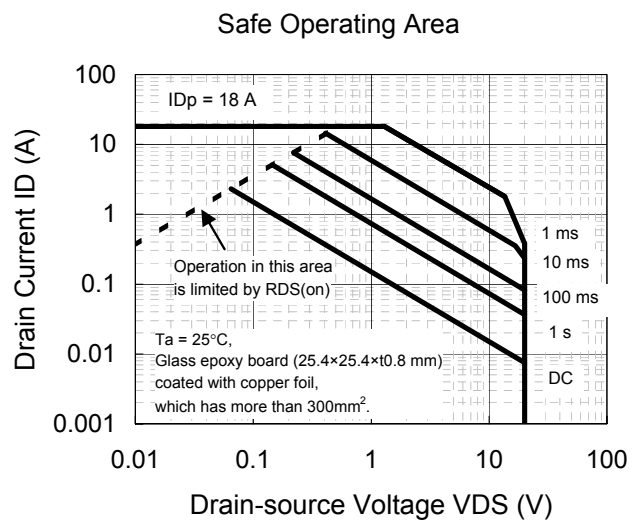
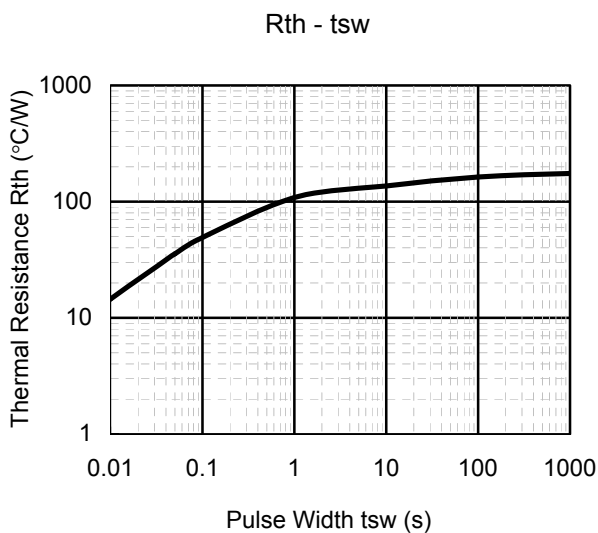
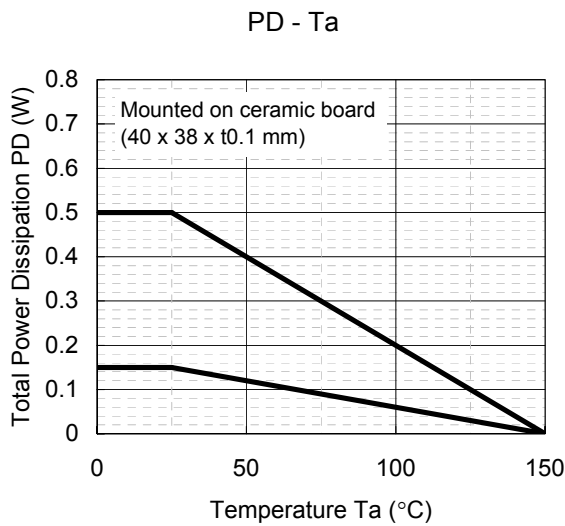
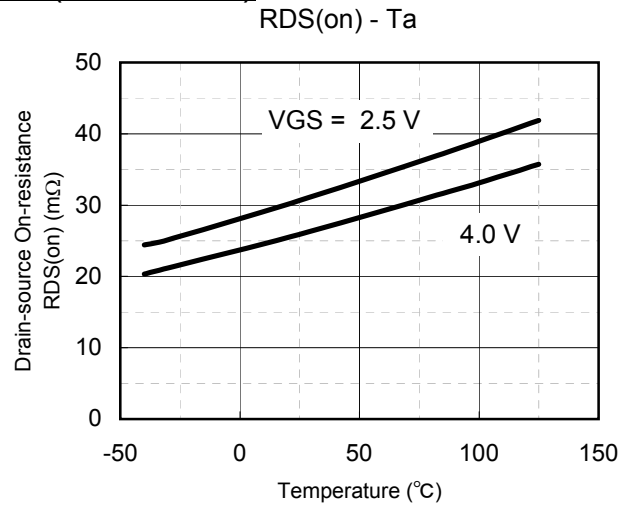
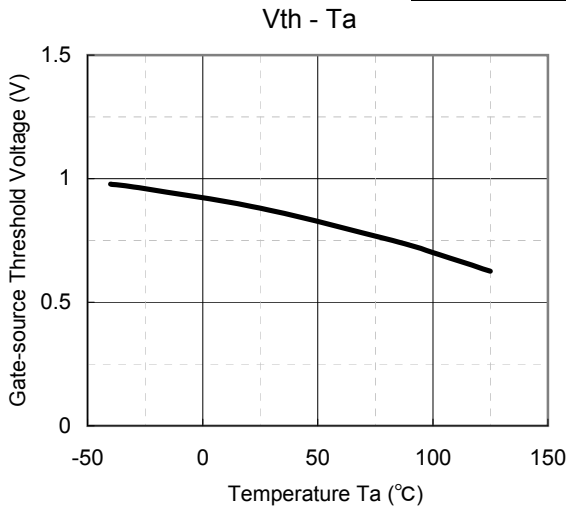
\*2 Turn-on and Turn-off test circuit



Technical Data ( reference )

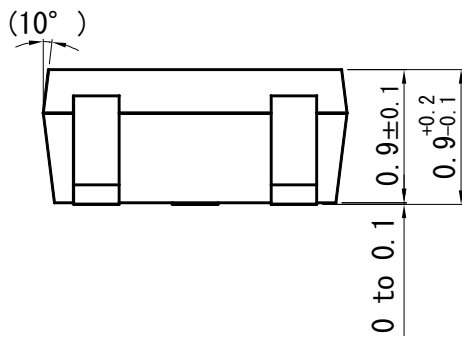
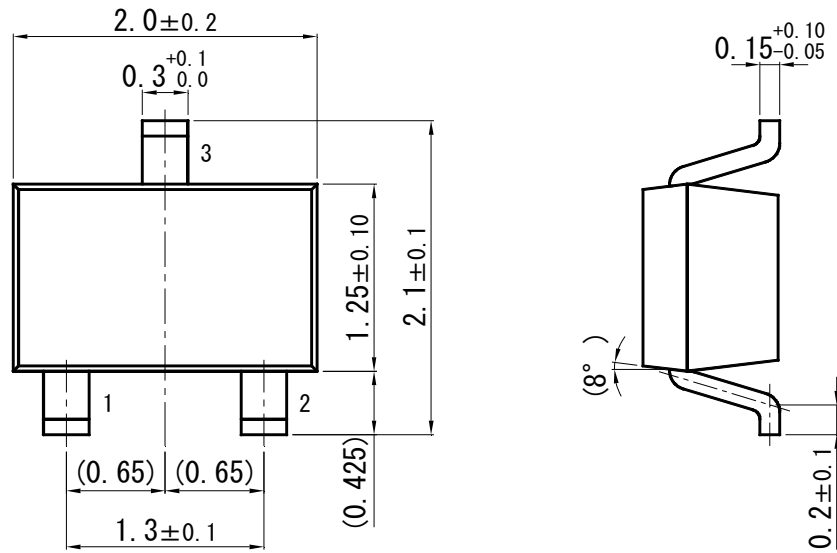


Technical Data ( reference )

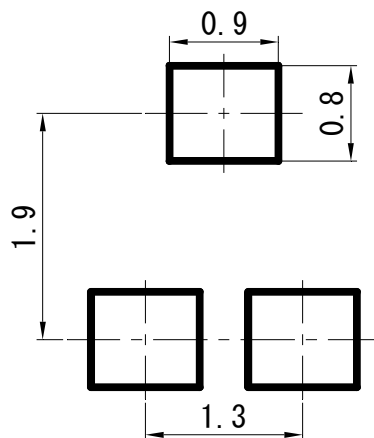




SMini3-G1-B



■ Land Pattern (Reference) (Unit : mm)



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